



HP ProLiant Servers Double Performance, Slash Energy Costs Up to 50 Percent

PALO ALTO, Calif., June 2, 2009 – HP today announced the addition of several new servers to its HP ProLiant server portfolio that provide advances in energy efficiency, performance and manageability, delivering increased value for every IT dollar.

Seven of the new HP ProLiant server platforms are built on the Six-Core AMD Opteron™ processors, delivering an unmatched price to performance ratio.

HP also introduced an entirely new HP ProLiant platform that offers double the density of traditional rack servers, resulting in more compute power with reduced energy use. In addition, a new modular, scalable tower server design enables customers to buy capacity as needed and defer capital expenditures by extending processing power and memory capacity in the server as the business grows.

“Customers want to cut costs from every corner of their data centers to help drive new business growth,” said Doug Oathout, vice president, Green IT, Enterprise Servers and Storage, HP. “By simply replacing servers purchased prior to 2006 with new HP ProLiant G6 servers, customers can slash their energy bills in half.”

Built for energy savings and performance

The most energy-efficient x86 servers in the industry, the new HP ProLiant G6 on AMD processors offer expanded availability of many energy-saving and performance features including:

- Thermal Logic technologies allow G6 servers to use half the power of previous generations,⁽¹⁾ including HP Dynamic Power Capping, which limits the power drawn by the server. Additionally, the Sea of Sensors uses up to 32 smart sensors in each server to automatically monitor the heat created by a server and adjusts fans accordingly.
- Common Slot Power Supplies offer up to 92 percent efficiency on nearly all workloads⁽²⁾ by allowing customers to choose from four power supplies to match their specific application, minimizing power waste.
- Smart Arrays deliver up to double the performance by combining the latest 6 gigabit (Gb) per second serial-attached SCSI (SAS) hard drive interconnects and optimized I/O bandwidth processing power.
- HP ProLiant Onboard Administrator simplifies server management by centralizing all critical embedded management aspects of the server including setup, health monitoring and power optimization.

Editorial contacts:

Erin Collopy, HP
+1 408 390 6783
erin.collopy@hp.com

Ellen Healy
Burson-Marsteller for HP
+1 617 406 1657
ellen.healy@bm.com

HP Media Hotline
+1 866 266 7272
pr@hp.com
www.hp.com/go/newsroom

Hewlett-Packard Company
3000 Hanover Street
Palo Alto, CA 94304
www.hp.com

The HP ProLiant G6 AMD portfolio, based on AMD Opteron 6-core processors, includes the HP ProLiant DL785, DL585, DL385 and DL165 rack-optimized servers and the HP ProLiant BL465, BL495c and BL685c server blades.

Built for maximum performance per watt

The new HP ProLiant DL1000 Multi-Node series delivers a 30 percent increase in energy efficiency compared to traditional rack servers.⁽¹⁾ The DL1000 series is available in multiple compute and storage configurations providing customers with the flexibility to meet varying application requirements. The series includes the DL4x170h G6, offering four server nodes in a single two-unit chassis and the HP ProLiant DL2x170h G6, which provides two server nodes with expanded I/O capabilities. Features and benefits include:

- Double the density of traditional rack servers in an industry-standard design – provides industry-leading density to deliver more compute power in existing data center floor space. Delivers 672 cores and 10 terabytes of memory in a 42-unit rack, the highest two processor in two unit (2P 2U) server DIMM density in the industry.⁽³⁾
- Shared power and cooling infrastructure – offers higher performance in existing data center floor space while lowering overall energy consumption. Delivers an 80 percent reduction in thermal components and a 50 percent reduction in power supplies.⁽⁴⁾
- 4-in-1 efficiency over traditional servers – provides the performance of four servers with the management benefits of a single system to deliver increased compute power while reducing management complexity. Delivers a 9 percent performance per watt and 31 percent power efficiency improvement over competitive rack servers.⁽¹⁾

Also announced is the HP ProLiant ML330 G6, the industry's only modular tower server based on Intel® Xeon® 5500 processors and DDR3 memory. The ML330 offers the first modular server architecture engineered to easily scale processing power and memory capacity in the server, as required. This enables customers to defer capital expenditures until additional performance or capacity is needed for business growth.

Pricing⁽⁵⁾ and availability

The new HP ProLiant G6 platforms on AMD processors are now shipping worldwide. Starting prices for the new HP ProLiant G6 servers range from \$1,679 to \$17,029 and vary based on specific configurations.

The HP ProLiant DL4x170h and the HP ProLiant DL2x170h G6 servers are available now with a starting price of \$4,909 and \$2,819, respectively.

The HP ProLiant ML330 G6 server is available now with a starting price of \$1,199.

More information on HP ProLiant servers is available at www.hp.com/go/proliant.

About HP

HP, the world's largest technology company, simplifies the technology experience for consumers and businesses with a portfolio that spans printing, personal computing, software, services and IT infrastructure. More information about HP (NYSE: HPQ) is available at <http://www.hp.com/>.

⁽¹⁾ Energy efficiency based on HP testing.

⁽²⁾ Based on HP-commissioned third-party analyst research.



(3) Based on comparing DL4x170h memory density to Dell XS-23 II and Super Micro 2U Twin.

(4) Compared to ProLiant G5 servers

(5) Estimated U.S. street prices. Actual prices may vary.

AMD and AMD Opteron are trademarks or registered trademarks of Advanced Micro Devices, Inc. in the United States and/or other jurisdictions. Microsoft and Windows are U.S. registered trademarks of Microsoft Corp. Oracle is a registered trademark of Oracle Corporation and/or its affiliates. Intel and Intel Xeon are trademarks of Intel Corporation in the U.S. and other countries.

This news advisory contains forward-looking statements that involve risks, uncertainties and assumptions. If such risks or uncertainties materialize or such assumptions prove incorrect, the results of HP and its consolidated subsidiaries could differ materially from those expressed or implied by such forward-looking statements and assumptions. All statements other than statements of historical fact are statements that could be deemed forward-looking statements, including but not limited to statements of the plans, strategies and objectives of management for future operations; any statements concerning expected development, performance or market share relating to products and services; any statements regarding anticipated operational and financial results; any statements of expectation or belief; and any statements of assumptions underlying any of the foregoing. Risks, uncertainties and assumptions include macroeconomic and geopolitical trends and events; the execution and performance of contracts by HP and its customers, suppliers and partners; the achievement of expected operational and financial results; and other risks that are described in HP's Quarterly Report on Form 10-Q for the fiscal quarter ended January 31, 2009 and HP's other filings with the Securities and Exchange Commission, including but not limited to HP's Annual Report on Form 10-K for the fiscal year ended October 31, 2008. HP assumes no obligation and does not intend to update these forward-looking statements.

© 2009 Hewlett-Packard Development Company, L.P. The information contained herein is subject to change without notice. The only warranties for HP products and services are set forth in the express warranty statements accompanying such products and services. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein.

